Preferred Device

Dual Series Schottky Barrier Diode

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage
- Pb-Free Package is Available

MAXIMUM RATINGS (T_J = 150°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	70	Volts

THERMAL CHARACTERISTICS

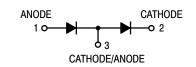
Characteristic	Symbol	Max	Unit
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	225 1.8	mW mW/°C
Operating Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C



ON Semiconductor®

http://onsemi.com

70 VOLTS SCHOTTKY BARRIER DIODE





SOT-23 (TO-236AB) CASE 318

MARKING DIAGRAM



CG = Specific Device Code

M = Date Code

ORDERING INFORMATION

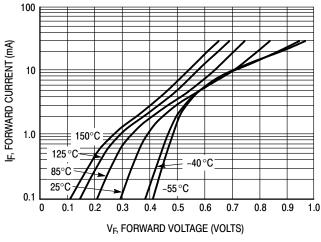
Device	Package	Shipping [†]
BAS70-04LT1	SOT-23	3000 / Tape & Reel
BAS70-04LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Syml	ool Min	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V _{(BR}) _R 70	_	Volts
Total Capacitance (V _R = 0 V, f = 1.0 MHz)	C _T		2.0	pF
Reverse Leakage ($V_R = 50 \text{ V}$) ($V_R = 70 \text{ V}$)	I _R		0.1 10	μAdc
Forward Voltage (I _F = 1.0 mAdc)	V _F	_	410	mVdc
Forward Voltage (I _F = 10 mAdc)	V _F	_	750	mVdc
Forward Voltage (I _F = 15 mAdc)	V _F	-	1.0	Vdc



100
T_A = 150°C

1.0
85°C

0.01
0.001
0 5.0 10 15 20 25 30 35 40 45 50
V_R, REVERSE VOLTAGE (VOLTS)

Figure 1. Typical Forward Voltage

Figure 2. Reverse Current versus Reverse Voltage

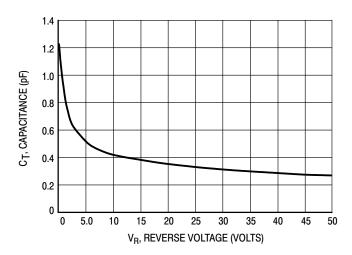
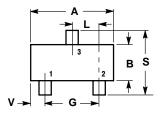


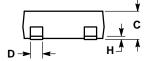
Figure 3. Typical Capacitance

PACKAGE DIMENSIONS

SOT-23 (TO-236AB) PLASTIC PACKAGÉ

CASE 318-08 **ISSUE AI**







NOTES:

- TITES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

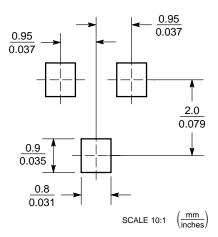
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
٧	0.0177	0.0236	0.45	0.60

STYLE 11: PIN 1. ANODE 2. CATHODE

3. CATHODE-ANODE

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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